Opening Remark Big Challenge for ICT Energy

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Ex-Officio and Thermal Management Chair INTELEC
On behalf of
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INTELEC President (IEEE PELS TC7 Chair)

The Seminar, Thermal Management of Electronic Systems ÅF, Grafiska vägen 2, 401 51 Göteborg November 27, 2018



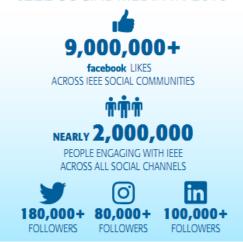


About IEEE

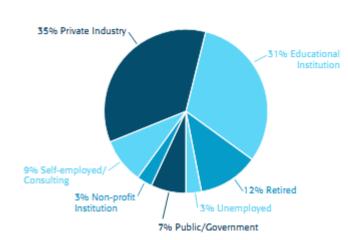


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IEEE SOCIAL MEDIA IN 2016







MEMBER WORKFORCE

Source: IEEE 2016 ANNUAL REPORT





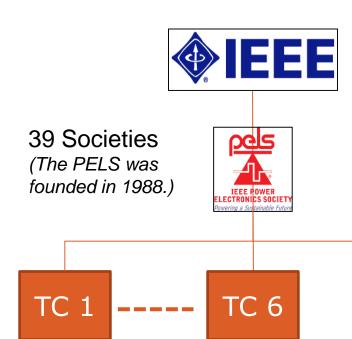
What is the INTELEC®, TC7?

INTELEC® is the IEEE trademark of the

International (Tele) Communications Energy Conference

It is a world-wide annual congress which began in 1978.

INTELEC has been sponsored by PELS since 1991.



IEEE Power Electronics Society, Technical Committees

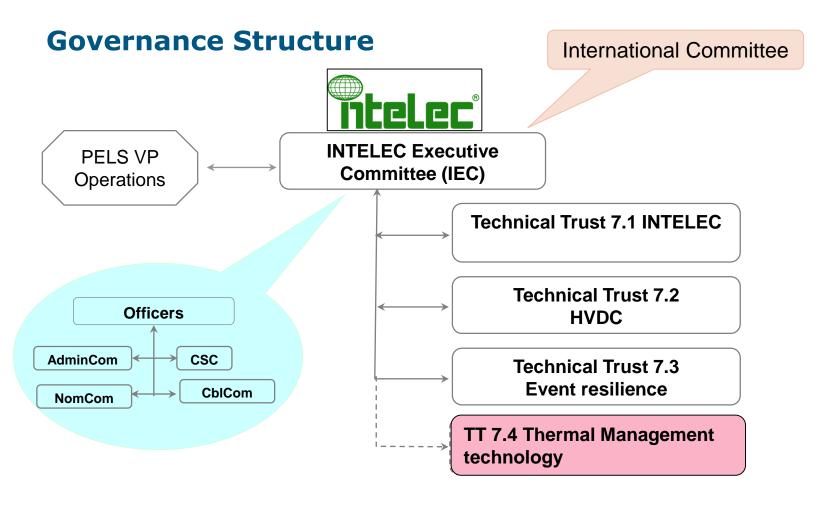
- TC 1: Power & Control Core Technologies
- TC 2: Power Conversion Systems And Components
- TC 3: Motor Drives and Actuators
- TC 4: Vehicle and Transportation Systems
- TC 5: Sustainable Energy Systems
- TC 6: High Performance and Emerging Technologies
- TC 7: Communication Energy Systems (INTELEC)







TC 7: Communications Energy Systems







INTELEC World-wide Venues

1978 Washington, DC, USA 1979 Washington, DC, USA 1981 London, UK 1982 Washington, DC, USA 1983 Tokyo, Japan 1984 New Orleans, USA 1985 Munich, Germany 1986 Toronto, Canada 1987 Stockholm, Sweden 1988 San Diego, USA 1989 Florence, Italy 1990 Orlando, USA 1991 Kyoto, Japan 1992 Washington, DC, USA 1993 Paris, France 1994 Vancouver, Canada 1995 The Hague, Netherlands

1999 Copenhagen, Denmark 2000 Phoenix, USA NA 2001 Edinburgh, UK 2002 Montreal, Canada **20** 2003 Yokohama, Japan 2004 Chicago, Illinois, USA 2005 Berlin, Germany 2006 Providence, RI, USA 2007 Rome, Italy **Europe** 2008 San Diego, USA **13** 2009 Incheon, South Korea 2010 Orlando, USA 2011 Amsterdam, Netherlands 2012 Scottsdale, USA 2013 Hamburg, Germany **APAC** 2014 Vancouver, Canada 2015 Osaka, Japan 2016 Austin, USA 2017 Gold coast. Australia 2018 Turin, Italy 2019 Singapore

2020 Malmö, Sweden

USA 16
Canada 4

Germany 3
Italy 3
UK 2
Netherlands 2
France 1
Sweden 1
Denmark 1

Japan 4
Australia 2

South Korea 1



1996 Boston, USA

1997 Melbourne, Australia

1998 San Francisco, USA



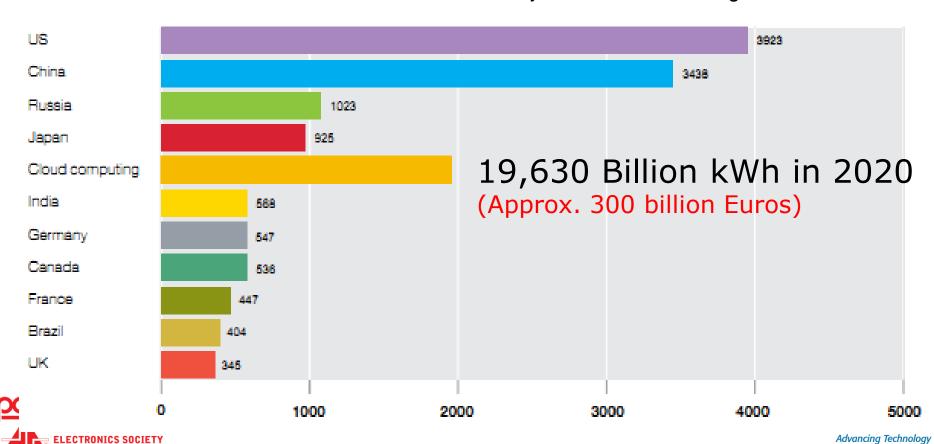
for Humanity

Electricity Consumption by ICT Services

Motivation 1: Energy saving and cost cut

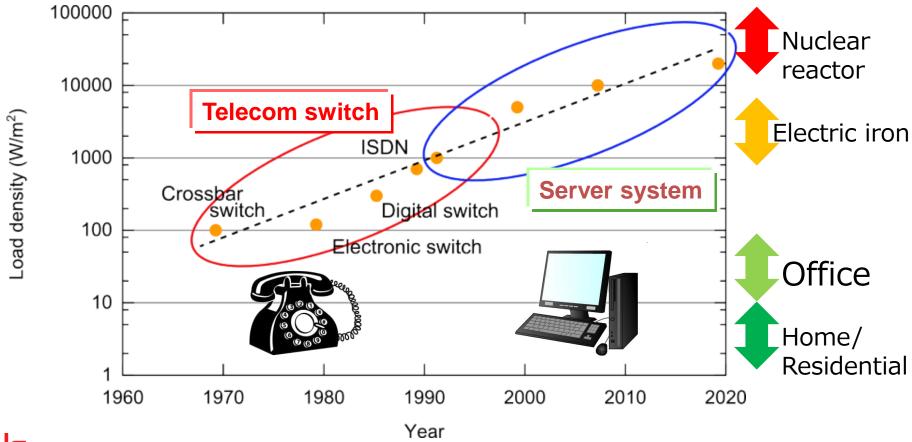
2007 electricity consumption. Billion kwH

Source: SMART 2020: Enabling the low carbon economy in the information age



Increasing Load Power Density for ICT services

Motivation 2: Requirement for High power density loads







Last Year's Seminar TMoES



2018

2017





























Together ahead. RUAG







Industrial partners from 7 to 16





TC on Communications Energy Systems

The 41st INTELEC 2019

13-17 October, 2019 Resorts World Sentosa, Singapore





















42nd Intelec, 2020 in Malmö Sweden



INTELEC 2020

Malmömässan, Malmö, Sweden 27th Sep. – 1st Oct.

Organizers and Sponsors:









Supported by:





We Can Do it!

INTELEC is one of the best communities to discuss the whole ICT energy issues world-wide. On other word, our community plays very important role to address these hot issues.

INTELEC would strongly support the thermal management area as a new technical trust (T.T 7.4).

Your contributions are essential for the *PELS* and *INTELEC* as well as ICT industry.

Let's get Experience and Knowledge together!





Coordinating Team



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